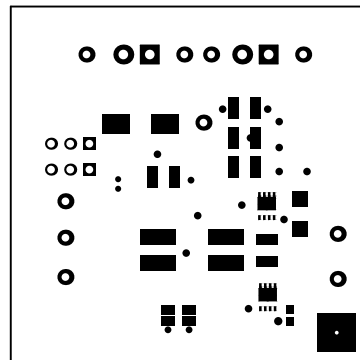
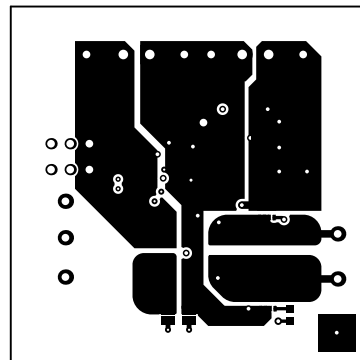


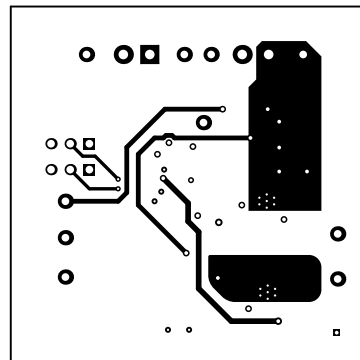
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 8/1/2017 13:08:40	TEXAS INSTRUMENTS	



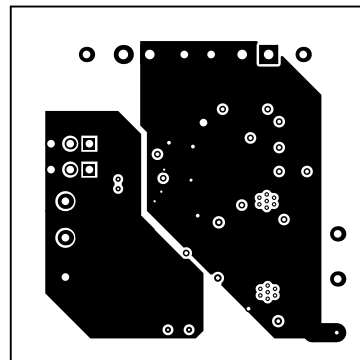
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 8/1/2017 13:08:41	TEXAS INSTRUMENTS	



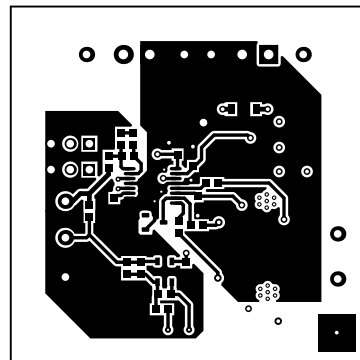
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 8/1/2017 13:08:42	TEXAS INSTRUMENTS	



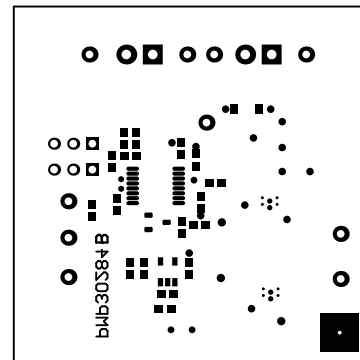
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #:		
PLOT NAME = Signal Layer 1	GENERATED : 8/1/2017 13:08:43	TEXAS INSTRUMENTS	



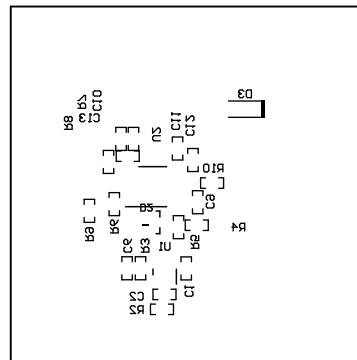
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #:		
PLOT NAME = Signal Layer 2	GENERATED : 8/1/2017 13:08:43	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 8/1/2017 13:08:44	TEXAS INSTRUMENTS	



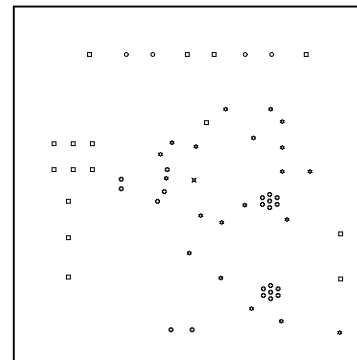
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/1/2017 13:08:45	TEXAS INSTRUMENTS	



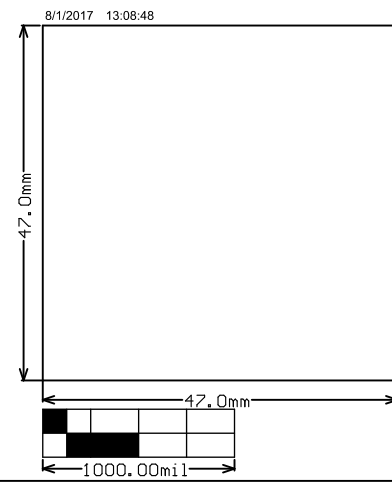
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 8/1/2017	13:08:46	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	21	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	1	0.400mm (15.75mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	20	0.500mm (19.69mil)	PTH	Round	Top Layer - Bottom Layer	
□	16	1.016mm (40.00mil)	PTH	Round	Top Layer - Bottom Layer	
○	4	1.270mm (50.00mil)	PTH	Round	Top Layer - Bottom Layer	
	62 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 8/1/2017	13:08:47	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 8/1/2017 13:08:48	TEXAS INSTRUMENTS	

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